

# IRPS 2016

## IEEE International Reliability Physics Symposium

### Sunday Tutorial Presentations

April 17, 2016

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TU1-1: Basics of Reliability Physics & Engineering - A Tutorial

TU1-2: FEOL Reliability - From Dielectric Trap Properties to Degradation Mechanisms and Their Distributions

TU1-3: Middle-of-Line Process Integration and Reliability Assessment Challenges

TU1-4: BEOL Reliability Challenges

TU2-1: The Physics of Flash Memory Reliability

TU2-2: Advanced Memory Technologies: CBRAM and OxRAM

TU2-3: 2.5D Packaging Reliability - Interposers and Fan Out Heterogeneous Integration

TU2-4: Reliability of 3D Through-Silicon-Via (TSV) Technologies

TU3-1: An Overview of Mechanical Reliability Challenges in Electronics Across Length Scales

TU3-3: Learning from and Reduction of IC Customer Returns

TU3-4: Security - What Are The Interactions of Hardware Faults with System Security?

